

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Jun Koyama	07/14/2011
RECEIVING PARTY DATA	
Name:	SEMICONDUCTOR ENERGY LABORATORY CO., LTD.
Street Address:	398, HASE
City:	ATSUGI-SHI, KANAGAWA-KEN
State/Country:	JAPAN
Postal Code:	243-0036
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14037450
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ATTORNEY DOCKET NUMBER:	12732-0908002
NAME OF SUBMITTER:	APRIL K. SAUNDERS-FULLER
Signature:	/April K. Saunders-Fuller/
Date:	03/05/2014
Total Attachments: 1 source=12732-0908002-ASN#page1.tif	

ASSIGNMENT

For valuable consideration, I, Jun KOYAMA of Sagami-hara, Kanagawa, Japan hereby assign to Semiconductor Energy Laboratory Co., Ltd., a Japanese corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by me this day, entitled **SEMICONDUCTOR INTEGRATED CIRCUIT**, filed 09/26/2013, and assigned U.S. Serial Number 14/037,450, and I authorize and request the Assignee or the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and I agree for myself and my respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature Jun Koyama
Name: Jun KOYAMA
Date: 07/14/2011